

ABSTRACT

A semiconductor sputtering process equipment is disclosed. The sputtering equipment comprises a cavity, a substrate support for the wafers, a contamination shutter disk and its carrier, and its calibration mechanism. The calibration mechanism is arranged on the cavity. The contamination shutter disk is switched between a first position and a second position by the carrier. When the shutter disk is at the first position, it is away from the substrate support. The calibration mechanism adjusts the shutter disk to a preset position on the carrier. When the shutter disk is at the preset position on the carrier and the carrier drives the shutter disk to move to the second position, the shutter disk is positioned above the substrate support, and a spacing between a first central axis of the shutter disk and a second central axis of the substrate support is less than or equal to a first preset distance.